

ESP32-SOLO-1

Datasheet



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Espressif Systems
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About This Document

This document provides the specifications for the ESP32-SOLO-1 module.

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For revision history of this document, please refer to the [last page](#).

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Contents

| | | |
|-----------|--|----|
| 1 | Overview | 6 |
| 2 | Pin Definitions | 8 |
| 2.1 | Pin Layout | 8 |
| 2.2 | Pin Description | 8 |
| 2.3 | Strapping Pins | 10 |
| 3 | Functional Description | 12 |
| 3.1 | CPU and Internal Memory | 12 |
| 3.2 | External Flash and SRAM | 12 |
| 3.3 | Crystal Oscillators | 12 |
| 3.4 | RTC and Low-Power Management | 13 |
| 4 | Peripherals and Sensors | 14 |
| 5 | Electrical Characteristics | 15 |
| 5.1 | Absolute Maximum Ratings | 15 |
| 5.2 | Recommended Operating Conditions | 15 |
| 5.3 | DC Characteristics (3.3 V, 25 °C) | 15 |
| 5.4 | Wi-Fi Radio | 16 |
| 5.5 | Bluetooth LE Radio | 17 |
| | 5.5.1 Receiver | 17 |
| | 5.5.2 Transmitter | 17 |
| 5.6 | Reflow Profile | 18 |
| 6 | Schematics | 19 |
| 7 | Peripheral Schematics | 20 |
| 8 | Physical Dimensions | 21 |
| 9 | Recommended PCB Land Pattern | 22 |
| 10 | Related Documentation and Resources | 23 |
| | Revision History | 24 |

List of Tables

| | | |
|----|--|----|
| 1 | ESP32-SOLO-1 Ordering Information | 6 |
| 2 | ESP32-SOLO-1 Specifications | 6 |
| 3 | Pin Definitions | 8 |
| 4 | Strapping Pins | 10 |
| 5 | Absolute Maximum Ratings | 15 |
| 6 | Recommended Operating Conditions | 15 |
| 7 | DC Characteristics (3.3 V, 25 °C) | 15 |
| 8 | Wi-Fi Radio Characteristics | 16 |
| 9 | Receiver Characteristics – Bluetooth LE | 17 |
| 10 | Transmitter Characteristics – Bluetooth LE | 17 |

List of Figures

| | | |
|---|--|----|
| 1 | ESP32-SOLO-1 Pin Layout (Top View) | 8 |
| 2 | Reflow Profile | 18 |
| 3 | ESP32-SOLO-1 Schematics | 19 |
| 4 | ESP32-SOLO-1 Peripheral Schematics | 20 |
| 5 | Physical Dimensions of ESP32-SOLO-1 | 21 |
| 6 | Recommended PCB Land Pattern of ESP32-SOLO-1 | 22 |

1 Overview

ESP32-SOLO-1 is a powerful, generic Wi-Fi + Bluetooth + Bluetooth LE MCU module that targets a wide variety of applications, ranging from low-power sensor networks to the most demanding tasks, such as voice encoding, music streaming and MP3 decoding.

Two different temperature variants of ESP32-SOLO-1 are available. Details are listed as follows:

Table 1: ESP32-SOLO-1 Ordering Information

| Module | Chip embedded | Recommended operating temperature range | Flash | Dimensions (mm) |
|----------------------------------|---------------|---|-------|-------------------|
| ESP32-SOLO-1 (Default Version) | ESP32-S0WD | -40 °C ~ +85 °C | 4 MB | 18 × 25.5 × 3.1 |
| ESP32-SOLO-1 (High Temp Version) | ESP32-S0WD | -40 °C ~ +105 °C | 4 MB | 18.0 × 25.5 × 3.1 |

For detailed ordering information, please see [ESP Product Selector](#). **The information in this datasheet is applicable to both modules.**

At the core of this module is the ESP32-S0WD chip. ESP32-S0WD is a member of the ESP32 family of chips, which features a single core and contains all the peripherals of its dual-core counterparts. Available in a 5×5 mm QFN, ESP32-S0WD offers great value for money, with its sustained performance when powering complex IoT applications.

Note:

* For details on the part numbers of the ESP32 family of chips, please refer to the document [ESP32 Datasheet](#).

The integration of Bluetooth, Bluetooth LE and Wi-Fi ensures that a wide range of applications can be targeted, and that the module is all-around: using Wi-Fi allows a large physical range and direct connection to the internet through a Wi-Fi router, while using Bluetooth allows the user to conveniently connect to the phone or broadcast low energy beacons for its detection. The sleep current of the ESP32 chip is less than 5 μ A, making it suitable for battery powered and wearable electronics applications. The module supports a data rate of up to 150 Mbps, and 20 dBm output power at the antenna to ensure the widest physical range. Several peripherals facilitate integration with other electronic devices. As such the chip does offer industry-leading specifications and ultra-high performance for electronic integration, range, power consumption, and connectivity.

The operating system chosen for ESP32 is freeRTOS with LwIP; TLS 1.2 with hardware acceleration is built in as well. Secure (encrypted) over the air (OTA) upgrade is also supported, so that developers can upgrade their products even after their release at minimum cost and effort.

Table 2 provides the specifications of ESP32-SOLO-1.

Table 2: ESP32-SOLO-1 Specifications

| Categories | Items | Specifications |
|---------------|---------------------|---|
| Certification | RF certification | See certificates for ESP32-SOLO-1 |
| | Wi-Fi certification | Wi-Fi Alliance |
| | Green certification | RoHS/REACH |

| Categories | Items | Specifications |
|------------|---|--|
| Test | Reliability | HTOL/HTSL/uHAST/TCT/ESD |
| Wi-Fi | Protocols | 802.11 b/g/n (802.11n up to 150 Mbps) A-MPDU and A-MSDU aggregation and 0.4 μ s guard interval support |
| | Center frequency range of operating channel | 2412 ~ 2484 MHz |
| Bluetooth | Protocols | Bluetooth v4.2 BR/EDR and Bluetooth LE specification |
| | Radio | NZIF receiver with -97 dBm sensitivity |
| | | Class-1, class-2 and class-3 transmitter AFH |
| Audio | CVSD and SBC | |
| Hardware | Module interfaces | SD card, UART, SPI, SDIO, I2C, LED PWM, Motor PWM, I2S, IR, pulse counter, GPIO, capacitive touch sensor, ADC, DAC, Two-Wire Automotive Interface (TWAI [®]), compatible with ISO11898-1 (CAN Specification 2.0) |
| | On-chip sensor | Hall sensor |
| | Integrated crystal | 40 MHz crystal |
| | Integrated SPI flash | 4 MB |
| | Operating voltage/Power supply | 3.0 V ~ 3.6 V |
| | Minimum current delivered by power supply | 500 mA |
| | Operating ambient temperature range | -40 °C ~ +85 °C or -40 °C ~ +105 °C |
| | Package size | 18 mm × 25.5 mm × 3.1 mm |
| | Moisture sensitivity level (MSL) | Level 3 |

2 Pin Definitions

2.1 Pin Layout

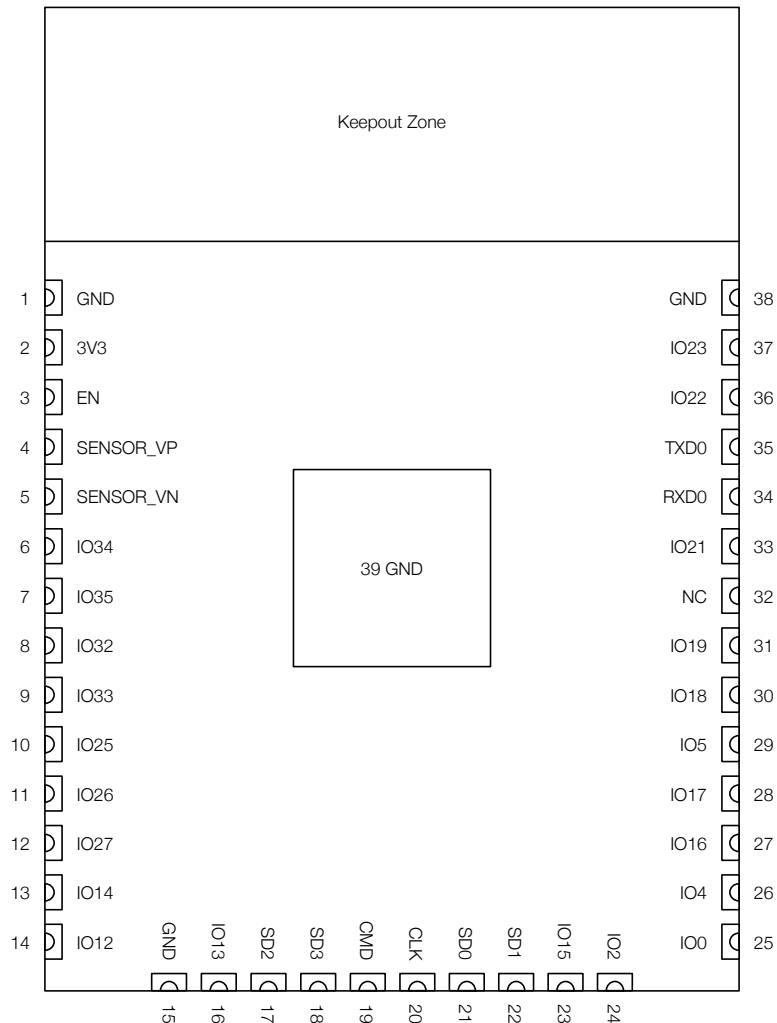


Figure 1: ESP32-SOLO-1 Pin Layout (Top View)

2.2 Pin Description

ESP32-SOLO-1 has 38 pins. See pin definitions in Table 3.

Table 3: Pin Definitions

| Name | No. | Type | Function |
|-----------|-----|------|------------------------------------|
| GND | 1 | P | Ground |
| 3V3 | 2 | P | Power supply |
| EN | 3 | I | Module-enable signal. Active high. |
| SENSOR_VP | 4 | I | GPIO36, ADC1_CH0, RTC_GPIO0 |
| SENSOR_VN | 5 | I | GPIO39, ADC1_CH3, RTC_GPIO3 |
| IO34 | 6 | I | GPIO34, ADC1_CH6, RTC_GPIO4 |

| Name | No. | Type | Function |
|----------|-----|------|--|
| IO35 | 7 | I | GPIO35, ADC1_CH7, RTC_GPIO5 |
| IO32 | 8 | I/O | GPIO32, XTAL_32K_P (32.768 kHz crystal oscillator input), ADC1_CH4, TOUCH9, RTC_GPIO9 |
| IO33 | 9 | I/O | GPIO33, XTAL_32K_N (32.768 kHz crystal oscillator output), ADC1_CH5, TOUCH8, RTC_GPIO8 |
| IO25 | 10 | I/O | GPIO25, DAC_1, ADC2_CH8, RTC_GPIO6, EMAC_RXD0 |
| IO26 | 11 | I/O | GPIO26, DAC_2, ADC2_CH9, RTC_GPIO7, EMAC_RXD1 |
| IO27 | 12 | I/O | GPIO27, ADC2_CH7, TOUCH7, RTC_GPIO17, EMAC_RX_DV |
| IO14 | 13 | I/O | GPIO14, ADC2_CH6, TOUCH6, RTC_GPIO16, MTMS, HSPICLK, HS2_CLK, SD_CLK, EMAC_TXD2 |
| IO12 | 14 | I/O | GPIO12, ADC2_CH5, TOUCH5, RTC_GPIO15, MTDI, HSPIQ, HS2_DATA2, SD_DATA2, EMAC_TXD3 |
| GND | 15 | P | Ground |
| IO13 | 16 | I/O | GPIO13, ADC2_CH4, TOUCH4, RTC_GPIO14, MTCK, HSPID, HS2_DATA3, SD_DATA3, EMAC_RX_ER |
| SHD/SD2* | 17 | I/O | GPIO9, SD_DATA2, SPIHD, HS1_DATA2, U1RXD |
| SWP/SD3* | 18 | I/O | GPIO10, SD_DATA3, SPIWP, HS1_DATA3, U1TXD |
| SCS/CMD* | 19 | I/O | GPIO11, SD_CMD, SPICS0, HS1_CMD, U1RTS |
| SCK/CLK* | 20 | I/O | GPIO6, SD_CLK, SPICLK, HS1_CLK, U1CTS |
| SDO/SD0* | 21 | I/O | GPIO7, SD_DATA0, SPIQ, HS1_DATA0, U2RTS |
| SDI/SD1* | 22 | I/O | GPIO8, SD_DATA1, SPID, HS1_DATA1, U2CTS |
| IO15 | 23 | I/O | GPIO15, ADC2_CH3, TOUCH3, MTDO, HSPICS0, RTC_GPIO13, HS2_CMD, SD_CMD, EMAC_RXD3 |
| IO2 | 24 | I/O | GPIO2, ADC2_CH2, TOUCH2, RTC_GPIO12, HSPIWP, HS2_DATA0, SD_DATA0 |
| IO0 | 25 | I/O | GPIO0, ADC2_CH1, TOUCH1, RTC_GPIO11, CLK_OUT1, EMAC_TX_CLK |
| IO4 | 26 | I/O | GPIO4, ADC2_CH0, TOUCH0, RTC_GPIO10, HSPICLK, HS2_DATA1, SD_DATA1, EMAC_TX_ER |
| IO16 | 27 | I/O | GPIO16, HS1_DATA4, U2RXD, EMAC_CLK_OUT |
| IO17 | 28 | I/O | GPIO17, HS1_DATA5, U2TXD, EMAC_CLK_OUT_180 |
| IO5 | 29 | I/O | GPIO5, VSPICS0, HS1_DATA6, EMAC_RX_CLK |
| IO18 | 30 | I/O | GPIO18, VSPICLK, HS1_DATA7 |
| IO19 | 31 | I/O | GPIO19, VSPIQ, U0CTS, EMAC_TXD0 |
| NC | 32 | - | - |
| IO21 | 33 | I/O | GPIO21, VSPIHD, EMAC_TX_EN |
| RXD0 | 34 | I/O | GPIO3, U0RXD, CLK_OUT2 |
| TXD0 | 35 | I/O | GPIO1, U0TXD, CLK_OUT3, EMAC_RXD2 |
| IO22 | 36 | I/O | GPIO22, VSPIWP, U0RTS, EMAC_TXD1 |
| IO23 | 37 | I/O | GPIO23, VSPID, HS1_STROBE |
| GND | 38 | P | Ground |

Notice:

* Pins SCK/CLK, SDO/SD0, SDI/SD1, SHD/SD2, SWP/SD3 and SCS/CMD, namely, GPIO6 to GPIO11 are connected

to the integrated SPI flash integrated on the module and are not recommended for other uses.

2.3 Strapping Pins

ESP32 has five strapping pins, which can be seen in Chapter 6 Schematics:

- MTDI
- GPIO0
- GPIO2
- MTDO
- GPIO5

Software can read the values of these five bits from register "GPIO_STRAPPING".

During the chip's system reset release (power-on-reset, RTC watchdog reset and brownout reset), the latches of the strapping pins sample the voltage level as strapping bits of "0" or "1", and hold these bits until the chip is powered down or shut down. The strapping bits configure the device's boot mode, the operating voltage of VDD_SDIO and other initial system settings.

Each strapping pin is connected to its internal pull-up/pull-down during the chip reset. Consequently, if a strapping pin is unconnected or the connected external circuit is high-impedance, the internal weak pull-up/pull-down will determine the default input level of the strapping pins.

To change the strapping bit values, users can apply the external pull-down/pull-up resistances, or use the host MCU's GPIOs to control the voltage level of these pins when powering on ESP32.

After reset release, the strapping pins work as normal-function pins.

Refer to Table 4 for a detailed boot-mode configuration by strapping pins.

Table 4: Strapping Pins

| Voltage of Internal LDO (VDD_SDIO) | | | | | |
|---|-----------|--------------------------|--------------------------|--------------------------|--------------------------|
| Pin | Default | 3.3 V | | 1.8 V | |
| MTDI | Pull-down | 0 | | 1 | |
| Bootling Mode | | | | | |
| Pin | Default | SPI Boot | | Download Boot | |
| GPIO0 | Pull-up | 1 | | 0 | |
| GPIO2 | Pull-down | Don't-care | | 0 | |
| Enabling/Disabling Debugging Log Print over U0TXD During Bootling | | | | | |
| Pin | Default | U0TXD Active | | U0TXD Silent | |
| MTDO | Pull-up | 1 | | 0 | |
| Timing of SDIO Slave | | | | | |
| Pin | Default | FE Sampling FE Output | FE Sampling RE Output | RE Sampling FE Output | RE Sampling RE Output |
| MTDO | Pull-up | 0 | 0 | 1 | 1 |
| GPIO5 | Pull-up | 0 | 1 | 0 | 1 |

Note:

- FE: falling-edge, RE: rising-edge.
- Firmware can configure register bits to change the settings of "Voltage of Internal LDO (VDD_SDIO)" and "Timing of SDIO Slave" after booting.

3 Functional Description

This chapter describes the modules and functions integrated in ESP32-SOLO-1.

3.1 CPU and Internal Memory

ESP32-S0WD contains one low-power Xtensa® 32-bit LX6 microprocessor. The internal memory includes:

- 448 KB of ROM for booting and core functions.
- 520 KB of on-chip SRAM for data and instructions.
- 8 KB of SRAM in RTC, which is called RTC FAST Memory and can be used for data storage; it is accessed by the main CPU during RTC Boot from the Deep-sleep mode.
- 8 KB of SRAM in RTC, which is called RTC SLOW Memory and can be accessed by the co-processor during the Deep-sleep mode.
- 1 Kbit of eFuse: 256 bits are used for the system (MAC address and chip configuration) and the remaining 768 bits are reserved for customer applications, including flash-encryption and chip-ID.

3.2 External Flash and SRAM

ESP32 supports multiple external QSPI flash and SRAM chips. More details can be found in Chapter SPI in the [ESP32 Technical Reference Manual](#). ESP32 also supports hardware encryption/decryption based on AES to protect developers' programs and data in flash.

ESP32 can access the external QSPI flash and SRAM through high-speed caches.

- The external flash can be mapped into CPU instruction memory space and read-only memory space simultaneously.
 - When external flash is mapped into CPU instruction memory space, up to 11 MB + 248 KB can be mapped at a time. Note that if more than 3 MB + 248 KB are mapped, cache performance will be reduced due to speculative reads by the CPU.
 - When external flash is mapped into read-only data memory space, up to 4 MB can be mapped at a time. 8-bit, 16-bit and 32-bit reads are supported.
- External SRAM can be mapped into CPU data memory space. Up to 4 MB can be mapped at a time. 8-bit, 16-bit and 32-bit reads and writes are supported.

ESP32-SOLO-1 integrates a 4 MB SPI flash, which is connected to GPIO6, GPIO7, GPIO8, GPIO9, GPIO10 and GPIO11. These six pins cannot be used as regular GPIOs.

3.3 Crystal Oscillators

The module uses a 40-MHz crystal oscillator.

3.4 RTC and Low-Power Management

With the use of advanced power-management technologies, ESP32 can switch between different power modes.

For details on ESP32's power consumption in different power modes, please refer to section "RTC and Low-Power Management" in [ESP32 Datasheet](#).

4 Peripherals and Sensors

Please refer to Section Peripherals and Sensors in [ESP32 Datasheet](#).

Note:

External connections can be made to any GPIO except for GPIOs in the range 6-11. These six GPIOs are connected to the module's integrated SPI flash. For details, please see Section 6 Schematics.

5 Electrical Characteristics

5.1 Absolute Maximum Ratings

Stresses beyond the absolute maximum ratings listed in Table 5 below may cause permanent damage to the device. These are stress ratings only, and do not refer to the functional operation of the device that should follow the [recommended operating conditions](#).

Table 5: Absolute Maximum Ratings

| Symbol | Parameter | Min | Max | Unit |
|----------------|------------------------------|------|-------|------|
| VDD33 | Power supply voltage | -0.3 | 3.6 | V |
| I_{output}^1 | Cumulative IO output current | - | 1,100 | mA |
| T_{store} | Storage temperature | -40 | 105 | °C |

1. The module worked properly after a 24-hour test in ambient temperature at 25 °C, and the IOs in three domains (VDD3P3_RTC, VDD3P3_CPU, VDD_SDIO) output high logic level to ground. Please note that pins occupied by flash and/or PSRAM in the VDD_SDIO power domain were excluded from the test.
2. Please see Appendix IO_MUX of [ESP32 Datasheet](#) for IO's power domain.

5.2 Recommended Operating Conditions

Table 6: Recommended Operating Conditions

| Symbol | Parameter | Min | Typ | Max | Unit |
|-----------|--|-----|-----|----------------------------------|------|
| VDD33 | Power supply voltage | 3.0 | 3.3 | 3.6 | V |
| I_{VDD} | Current delivered by external power supply | 0.5 | - | - | A |
| T | Operating ambient temperature | -40 | - | 85 or 105, depending on model | °C |

5.3 DC Characteristics (3.3 V, 25 °C)

Table 7: DC Characteristics (3.3 V, 25 °C)

| Symbol | Parameter | Min | Typ | Max | Unit | |
|----------|--|--|-----|---------------------|------|----|
| C_{IN} | Pin capacitance | - | 2 | - | pF | |
| V_{IH} | High-level input voltage | $0.75 \times VDD^1$ | - | $VDD^1 + 0.3$ | V | |
| V_{IL} | Low-level input voltage | -0.3 | - | $0.25 \times VDD^1$ | V | |
| I_{IH} | High-level input current | - | - | 50 | nA | |
| I_{IL} | Low-level input current | - | - | 50 | nA | |
| V_{OH} | High-level output voltage | $0.8 \times VDD^1$ | - | - | V | |
| V_{OL} | Low-level output voltage | - | - | $0.1 \times VDD^1$ | V | |
| I_{OH} | High-level source current ($VDD^1 = 3.3$ V, $V_{OH} \geq 2.64$ V, output drive strength set to the maximum) | VDD3P3_CPU power domain ^{1, 2} | - | 40 | - | mA |
| | | VDD3P3_RTC power domain ^{1, 2} | - | 40 | - | mA |

| Symbol | Parameter | Min | Typ | Max | Unit |
|----------------------|--|-----|-----|-----|------|
| | VDD_SDIO power domain ^{1, 3} | - | 20 | - | mA |
| I_{OL} | Low-level sink current (VDD ¹ = 3.3 V, V _{OL} = 0.495 V, output drive strength set to the maximum) | - | 28 | - | mA |
| R _{PU} | Resistance of internal pull-up resistor | - | 45 | - | kΩ |
| R _{PD} | Resistance of internal pull-down resistor | - | 45 | - | kΩ |
| V _{IL_nRST} | Low-level input voltage of CHIP_PU to power off the chip | - | - | 0.6 | V |

Notes:

1. Please see Appendix IO_MUX of [ESP32 Datasheet](#) for IO's power domain. VDD is the I/O voltage for a particular power domain of pins.
2. For VDD3P3_CPU and VDD3P3_RTC power domain, per-pin current sourced in the same domain is gradually reduced from around 40 mA to around 29 mA, V_{OH}>=2.64 V, as the number of current-source pins increases.
3. Pins occupied by flash and/or PSRAM in the VDD_SDIO power domain were excluded from the test.

5.4 Wi-Fi Radio

Table 8: Wi-Fi Radio Characteristics

| Parameter | Condition | Min | Typical | Max | Unit |
|--|-----------------|------|---------------|------|------|
| Center frequency range of operating channel ^{note1} | - | 2412 | - | 2484 | MHz |
| Output impedance ^{note2} | - | - | <i>note 2</i> | - | Ω |
| TX power ^{note3} | 11n, MCS7 | 12 | 13 | 14 | dBm |
| | 11b mode | 17.5 | 18.5 | 20 | dBm |
| Sensitivity | 11b, 1 Mbps | - | -98 | - | dBm |
| | 11b, 11 Mbps | - | -89 | - | dBm |
| | 11g, 6 Mbps | - | -92 | - | dBm |
| | 11g, 54 Mbps | - | -74 | - | dBm |
| | 11n, HT20, MCS0 | - | -91 | - | dBm |
| | 11n, HT20, MCS7 | - | -71 | - | dBm |
| | 11n, HT40, MCS0 | - | -89 | - | dBm |
| | 11n, HT40, MCS7 | - | -69 | - | dBm |
| Adjacent channel rejection | 11g, 6 Mbps | - | 31 | - | dB |
| | 11g, 54 Mbps | - | 14 | - | dB |
| | 11n, HT20, MCS0 | - | 31 | - | dB |
| | 11n, HT20, MCS7 | - | 13 | - | dB |

1. Device should operate in the center frequency range of operating channel allocated by regional regulatory authorities. Target center frequency range of operating channel is configurable by software.
2. For the modules that use external antennas, the output impedance is 50 Ω. For other modules without external antennas, users do not need to concern about the output impedance.
3. Target TX power is configurable based on device or certification requirements.

5.5 Bluetooth LE Radio

5.5.1 Receiver

Table 9: Receiver Characteristics – Bluetooth LE

| Parameter | Conditions | Min | Typ | Max | Unit |
|------------------------------------|---------------------------|-----|-----|-----|------|
| Sensitivity @30.8% PER | - | - | -97 | - | dBm |
| Maximum received signal @30.8% PER | - | 0 | - | - | dBm |
| Co-channel C/I | - | - | +10 | - | dB |
| Adjacent channel selectivity C/I | $F = F_0 + 1 \text{ MHz}$ | - | -5 | - | dB |
| | $F = F_0 - 1 \text{ MHz}$ | - | -5 | - | dB |
| | $F = F_0 + 2 \text{ MHz}$ | - | -25 | - | dB |
| | $F = F_0 - 2 \text{ MHz}$ | - | -35 | - | dB |
| | $F = F_0 + 3 \text{ MHz}$ | - | -25 | - | dB |
| | $F = F_0 - 3 \text{ MHz}$ | - | -45 | - | dB |
| Out-of-band blocking performance | 30 MHz ~ 2000 MHz | -10 | - | - | dBm |
| | 2000 MHz ~ 2400 MHz | -27 | - | - | dBm |
| | 2500 MHz ~ 3000 MHz | -27 | - | - | dBm |
| | 3000 MHz ~ 12.5 GHz | -10 | - | - | dBm |
| Intermodulation | - | -36 | - | - | dBm |

5.5.2 Transmitter

Table 10: Transmitter Characteristics – Bluetooth LE

| Parameter | Conditions | Min | Typ | Max | Unit |
|---|-------------------------------|-----|------|-----|----------------|
| RF transmit power | - | - | 0 | - | dBm |
| Gain control step | - | - | 3 | - | dB |
| RF power control range | - | -12 | - | +9 | dBm |
| Adjacent channel transmit power | $F = F_0 \pm 2 \text{ MHz}$ | - | -52 | - | dBm |
| | $F = F_0 \pm 3 \text{ MHz}$ | - | -58 | - | dBm |
| | $F = F_0 \pm > 3 \text{ MHz}$ | - | -60 | - | dBm |
| $\Delta f_{1\text{avg}}$ | - | - | - | 265 | kHz |
| $\Delta f_{2\text{max}}$ | - | 247 | - | - | kHz |
| $\Delta f_{2\text{avg}}/\Delta f_{1\text{avg}}$ | - | - | 0.92 | - | - |
| ICFT | - | - | -10 | - | kHz |
| Drift rate | - | - | 0.7 | - | kHz/50 μ s |
| Drift | - | - | 2 | - | kHz |

5.6 Reflow Profile

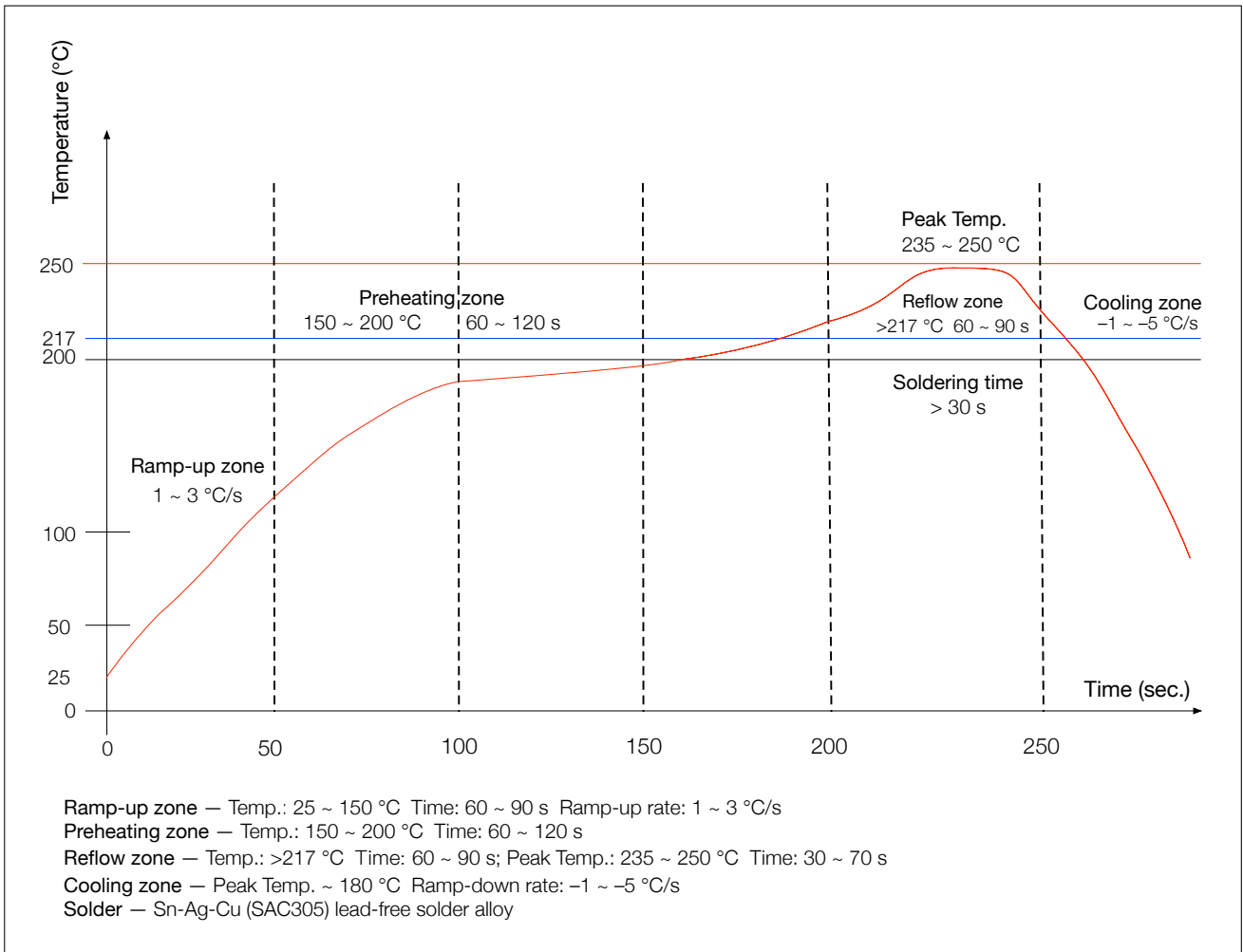


Figure 2: Reflow Profile

Note:

Solder the module in a single reflow.

6 Schematics

This is the reference design of the module.

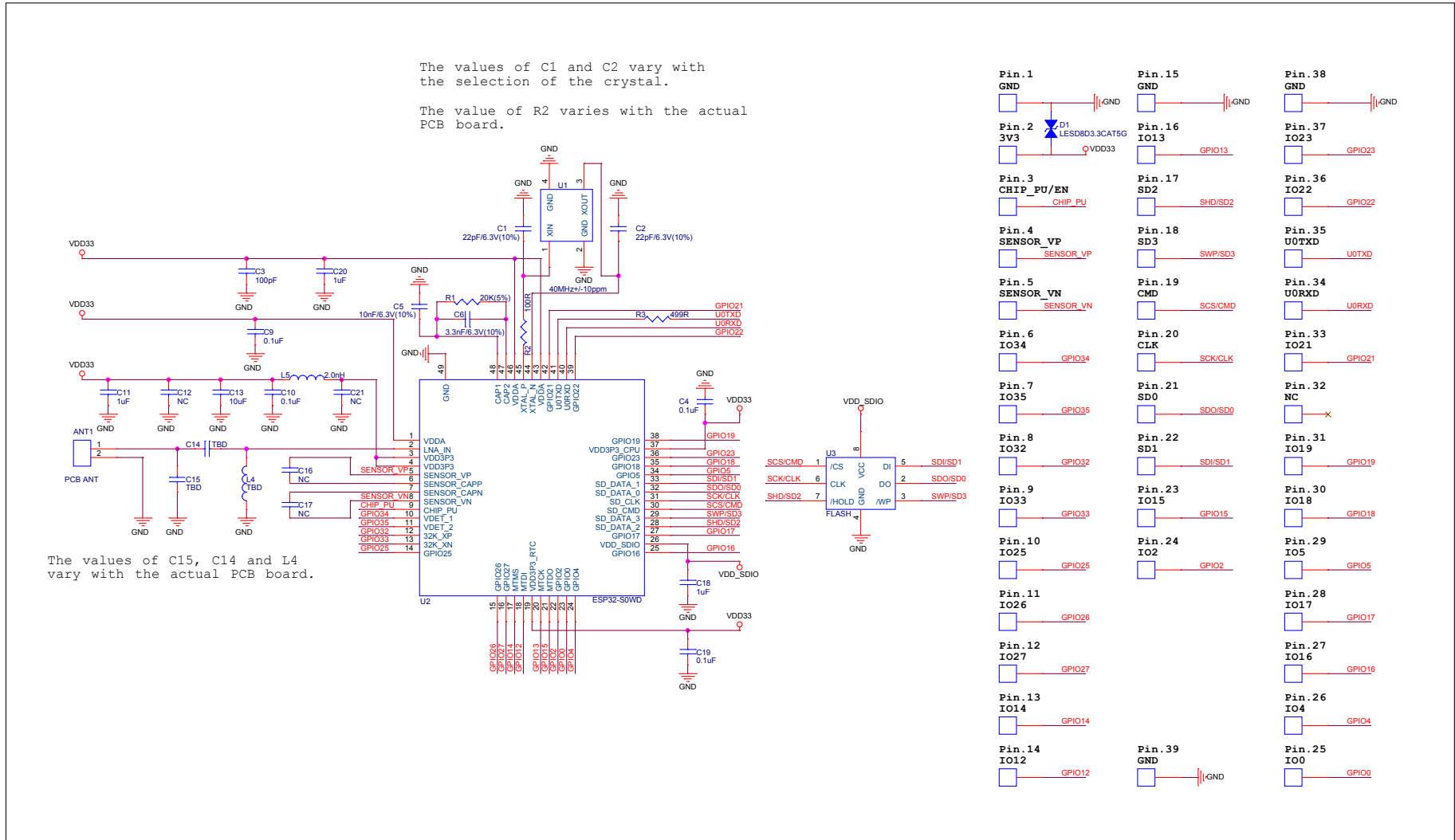


Figure 3: ESP32-SOLO-1 Schematics

7 Peripheral Schematics

This is the typical application circuit of the module connected with peripheral components (for example, power supply, antenna, reset button, JTAG interface, and UART interface).

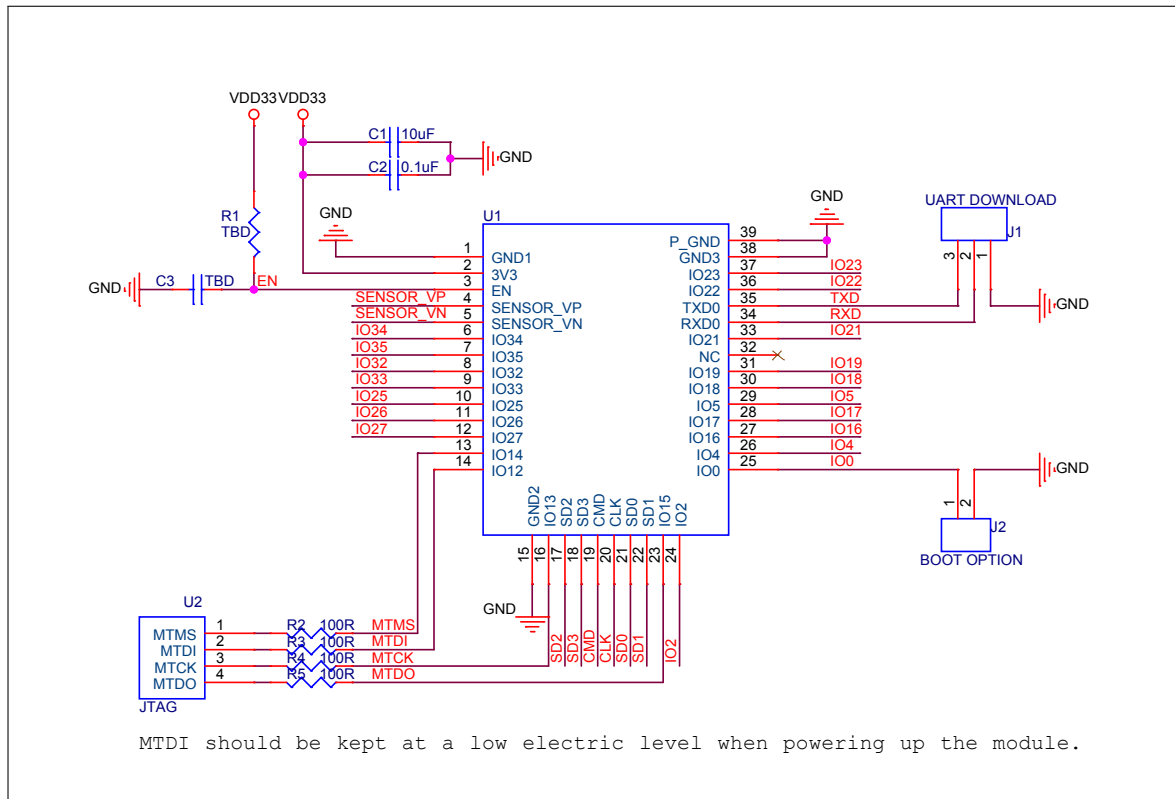


Figure 4: ESP32-SOLO-1 Peripheral Schematics

Note:

- Soldering Pad 39 to the Ground of the base board is not necessary for a satisfactory thermal performance. If users do want to solder it, they need to ensure that the correct quantity of soldering paste is applied.
- To ensure the power supply to the ESP32 chip during power-up, it is advised to add an RC delay circuit at the EN pin. The recommended setting for the RC delay circuit is usually $R = 10 \text{ k}\Omega$ and $C = 1 \mu\text{F}$. However, specific parameters should be adjusted based on the power-up timing of the module and the power-up and reset sequence timing of the chip. For ESP32's power-up and reset sequence timing diagram, please refer to Section *Power Scheme* in [ESP32 Datasheet](#).

8 Physical Dimensions

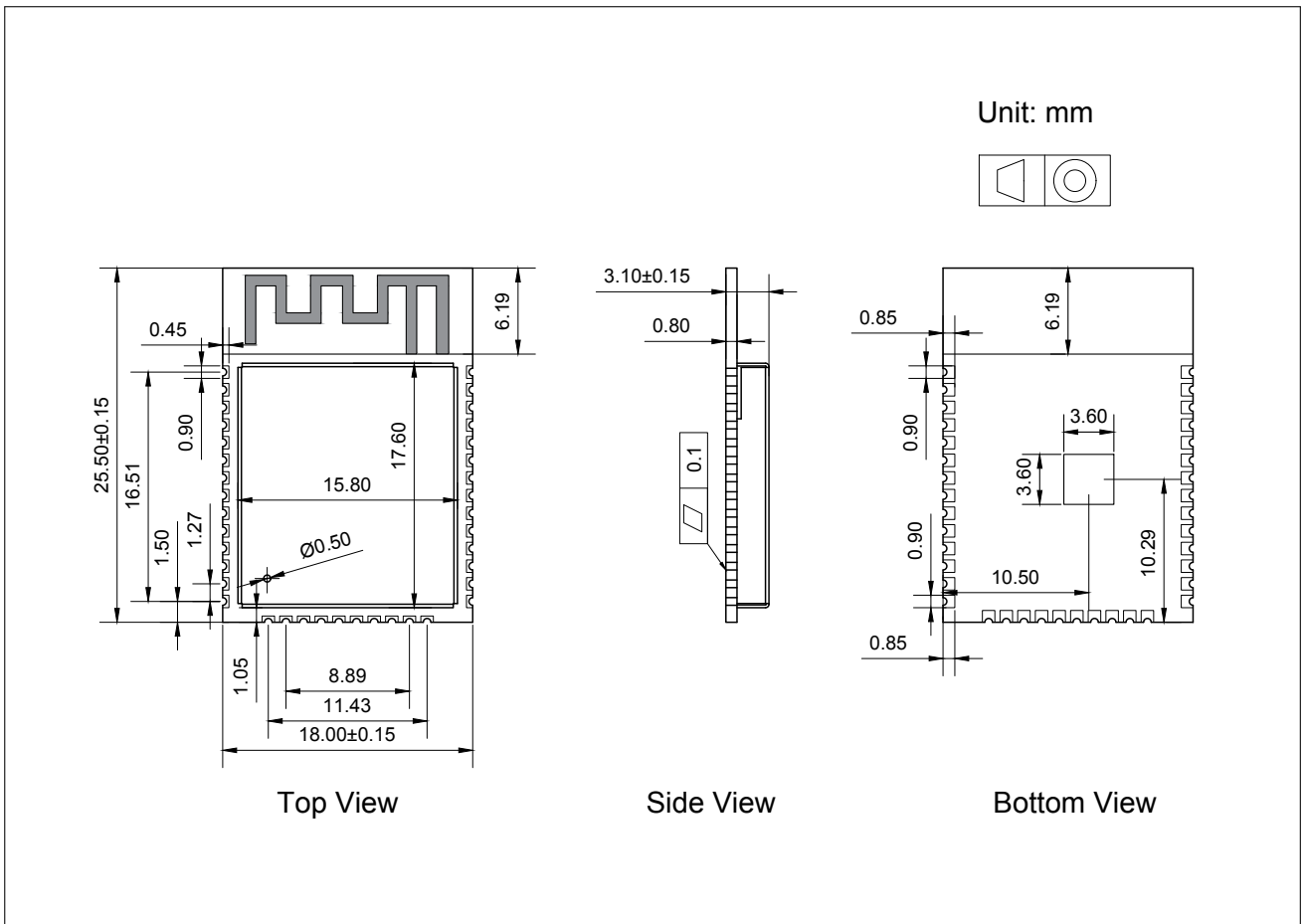


Figure 5: Physical Dimensions of ESP32-SOLO-1

Note:

For information about tape, reel, and product marking, please refer to [Espressif Module Package Information](#).

9 Recommended PCB Land Pattern

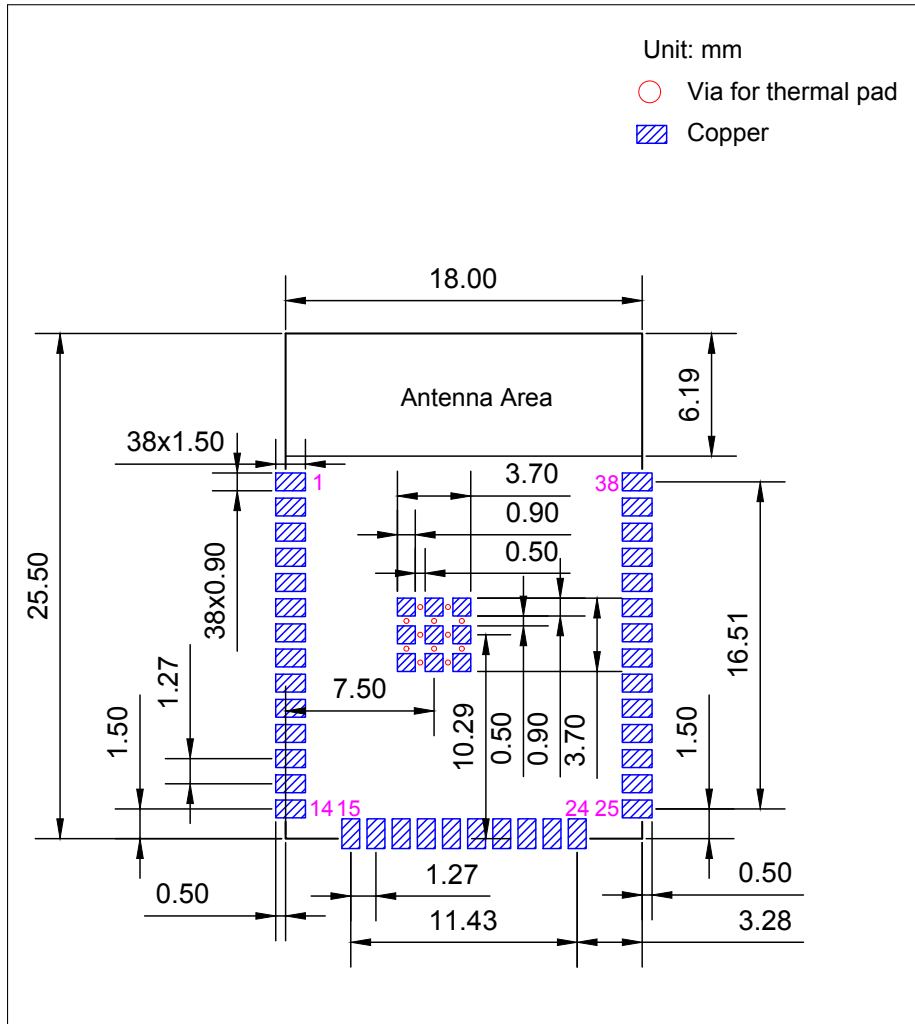


Figure 6: Recommended PCB Land Pattern of ESP32-SOLO-1

10 Related Documentation and Resources

Related Documentation

- [ESP32 Technical Reference Manual](#) – Detailed information on how to use the ESP32 memory and peripherals.
- [ESP32 Hardware Design Guidelines](#) – Guidelines on how to integrate the ESP32 into your hardware product.
- [ESP32 ECO and Workarounds for Bugs](#) – Correction of ESP32 design errors.
- *Certificates*
<https://espressif.com/en/support/documents/certificates>
- *ESP32 Product/Process Change Notifications (PCN)*
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Revision History

| Date | Version | Release notes |
|------------|---------|--|
| 2022-03-04 | v1.9 | <p>Updated Table 1</p> <p>Added a link to RF certificates in Table 2</p> <p>Updated Table 5</p> <p>Added a note below Figure 5</p> <p>Added Section 10: <i>Related Documentation and Resources</i></p> <p>Replaced Espressif Product Ordering Information with ESP Product Selector</p> |
| 2021-02-04 | V1.8 | <p>Updated Figure 5: <i>Physical Dimensions of ESP32-SOLO-1</i> and Figure 6: <i>Recommended PCB Land Pattern of ESP32-SOLO-1</i>.</p> <p>Modified the note below Figure 2: <i>Reflow Profile</i>.</p> <p>Updated the trade mark from TWAI™ to TWAI®.</p> |
| 2020-11-27 | V1.7 | <p>Added TWAI™ in Table 2;</p> <p>Updated Figure 2 and added a note under it;</p> <p>Added notes about schematics and peripheral schematics;</p> <p>Fixed some typos;</p> <p>Updated the C value in RC delay circuit from 0.1 μF to 1 μF;</p> <p>Provided feedback link.</p> |
| 2019.09 | V1.6 | <p>Changed the supply voltage range from 2.7 V ~ 3.6 V to 3.0 V ~ 3.6 V;</p> <p>Updated Section 7 <i>Peripheral Schematics</i> and added a note about RC delay circuit under it;</p> <p>Updated Figure 9 <i>Recommended PCB Land Pattern</i>.</p> |
| 2019.07 | V1.5 | <p>Added a new variant with high temperature range ($-40\text{ }^{\circ}\text{C} \sim +105\text{ }^{\circ}\text{C}$) in Chapter 1 <i>Overview</i>;</p> <p>Added Moisture sensitivity level (MSL) 3 in Table 2 <i>ESP32-SOLO-1 Specifications</i>;</p> <p>Added notes about "Operating frequency range" and "TX power" under Table 8 <i>Wi-Fi Radio Characteristics</i>.</p> |
| 2019.01 | V1.4 | <p>Changed the RF power control range in Table 10 from $-12 \sim +12$ to $-12 \sim +9$ dBm.</p> |
| 2018.09 | V1.3 | <ul style="list-style-type: none"> Updated the descriptions of pins IO16 and IO17 in Table 3: Pin Definitions; Added "Cumulative IO output current" entry to Table 5: Absolute Maximum Ratings; Added more parameters to Table 7: DC Characteristics. |
| 2018.09 | V1.2 | <p>Updated the hole diameter in the shield from 1.00 mm to 0.50 mm, in Figure 5. Added RoHS certification.</p> |

| Date | Version | Release notes |
|---------|---------|--|
| 2018.08 | V1.1 | <ul style="list-style-type: none">• Added certifications and reliability test items the module has passed in Table 2: ESP32-SOLO-1 Specifications, and removed software-specific information;• Updated section 3.4: RTC and Low-Power Management;• Changed the modules' dimensions from (18±0.2) mm x (25.5 ±0.2) mm x (3.1±0.15) mm to (18.00±0.10) mm x (25.50±0.10) mm x (3.10±0.10) mm;• Updated Table 8: Wi-Fi Radio;• Updated Figure 8: Physical Dimensions. |
| 2018.06 | V1.0 | First release. |



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